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Material Declaration Data Sheet

Product: **Server System SR1425BK1**   Manufacturer: Intel Corporation
Note: This declaration applies to all associated product codes noted on Page 2

Lead Free (Pb) Product: **NO**   Date: June 9, 2006

Restriction on Hazardous Substances (RoHS) Compliance

RoHS Definition
- Quantity limit of 0.1% by mass (1000PPM) for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE)
- Quantity limit of 0.01% by mass (100 PPM) for: Cadmium

Intel understands RoHS requires: Lead and other materials banned in the RoHS Directive are either (1) below all applicable substance thresholds as proposed by the EU or (2) an approved/pending exemption applies. (Note: RoHS implementing details are not fully defined and may change.)

RoHS Declaration

☐   1. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
☐   2. Lead as an alloying element in steel containing up to 0.35 % lead by weight.
☐   3. Lead as an alloying element in aluminum containing up to 0.4 % lead by weight.
☐   4. Lead as an alloying element in copper containing up to 4 % lead by weight.
☐   5. Lead in high melting temperature type solders (i.e. lead based alloys containing 85 % by weight or more lead)
☒   6. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.
☐   7. Lead in electronic ceramic parts (e.g. piezoelectronic devices).
☐   8. Lead used in compliant pin connector systems.
☐   9. Lead as a coating material for the thermal conduction module c-ring.
☐   10. Lead in optical and filter glass.
☐   11. Lead in solders consisting of more than two parts for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight.
☐   12. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.
☐   13. Cadmium in optical and filter glass.
☐   14. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (*) amending Directive 76/769/EEC (**) relating to restrictions on the marketing and use of certain dangerous substances and preparations.
☐   15. Lead in bronze bearing shells and brushes.
☐   16. Other

Where the product is declared to meet RoHS requirements, it has been verified to be in conformance with 2002/95/EC as we currently understand the requirements. Intel has systems in place to verify conformance with all applicable environmental requirements and to the best of our knowledge the information is true and correct.

Product Code Information

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Product Code	Description	*RoHS Exemption #
A1400SATAKIT	PROD CODE,EKIT,1U SATA HSBP	,6
A1400SCSIKIT	PROD CODE,EKIT,1U SCSI HSBP	,6
ABKPCIEXPUP	PROD CODE,1U, PCI-E RISER, GOLD	,6
ABKPCIXUP	PROD CODE,1U, PCI-X RISER, GOLD	,6
ABKSCSICABLE	PC, FIXED HD KIT	None
ADWBEZBLACK	PROD CODE, STD FP OUTER BEZEL	None
AXXBKHS	PC, HEATSINK KIT	None
AXXBRACKETS	PROD CODE, BRACKET MOUNTING KIT	None
AXXDVDCDR	PCODE, CDR/DVD WRITES CDS READS DVD	None
AXXHERAIL	PROD CODE,RAIL KIT, HE	None
AXXRACKCARM	PROD CODE,CABLE ARM, KIT	None
AXXSCD	PROD CODE,AXXSCD	None
AXXSFLOPPY	PROD CODE,AXXSFLOPPY	None
BBKBB	PC,SKU1,10 PACK	,6
BBKBBLX	PC,SKU2,10 PACK	,6
FBK1UCHSPRKIT	PC, CHASSIS SPR KIT	,6
FBKFANUP	PC, FAN KIT	None
FPTCOSMKIT	PROD CODE, BEZEL KIT	None
FXXCBL300K	PC,300W PWR SUPPLY	None
SE7221BK1	PROD CODE, BOXED BRD,GOLD, 1GBE	,6
SE7221BK1LX	PROD CODE, BOXED BRD,GOLD, 2GBE	,6
SR1425BK1	PROD CODE SR1425BK1	,6
SR1425BK1NA	PROD CODE SR1425BK1NA	,6

* RoHS Exemption # corresponds with exemption #'s found on page 1.